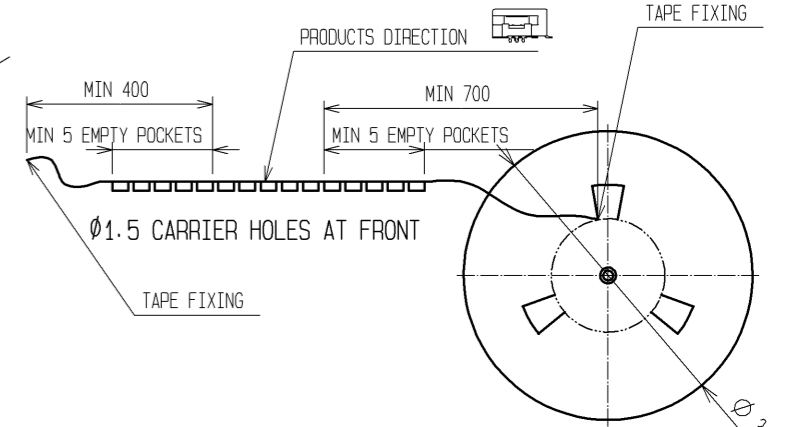
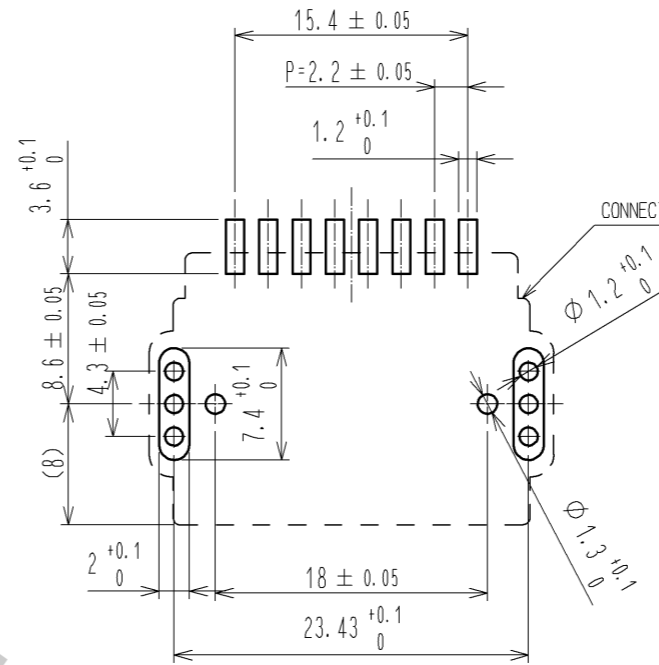
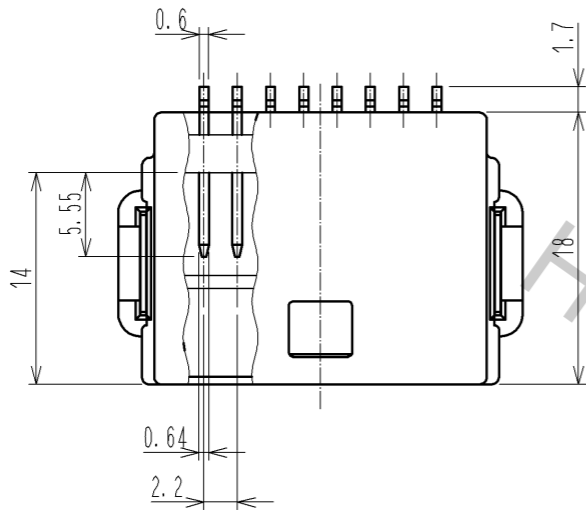
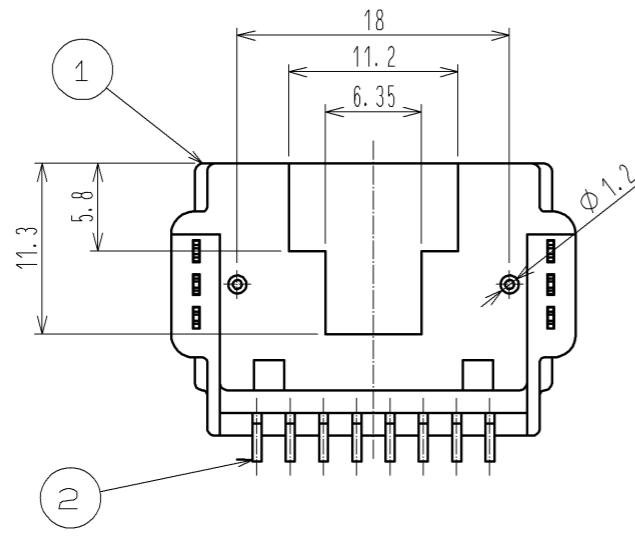
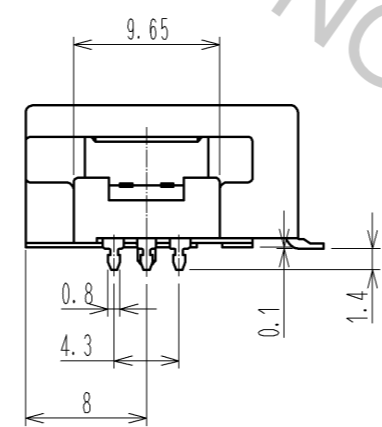
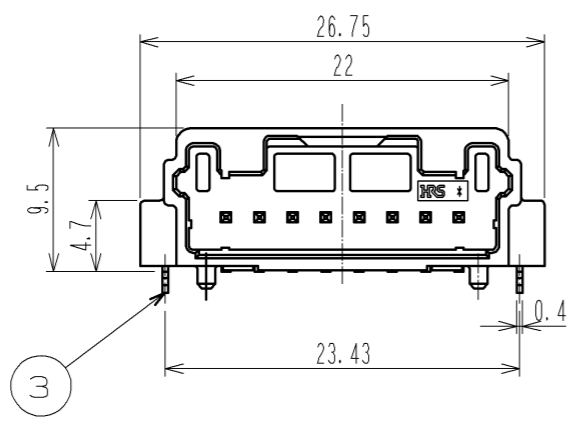


ELV, RoHS

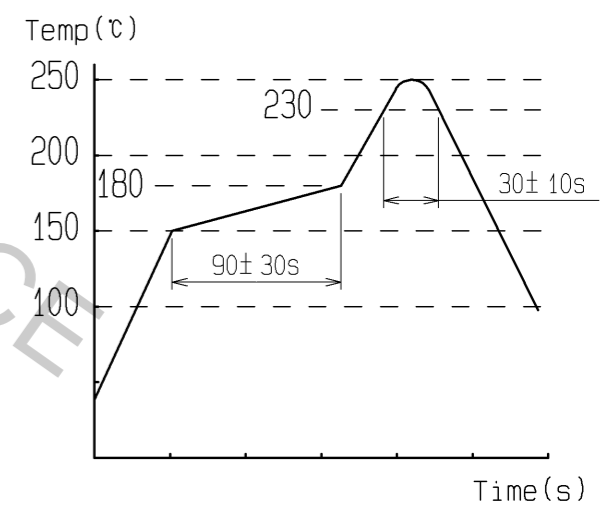


RECOMMENDED PC BOARD PATTERN

EMBOSS SPECULATION



- NOTE1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW
(REFER TO RIGHT FIG.)
USED REFLOW SYSTEM
: IR IN THE AIR OR NITROGEN
NO. OF CYCLES : 2 TIMES
PEAK : 250°C
OVER 230°C : 20~40s
PREHEAT : 150~180°C
60~120s
2. TEMPERATURE FOR SOLDERING IRON
: 280~300°C WITHIN 2s
3. CO-PLANARITY SHALL BE 0.1 MAX.
4. PC BOARD THICKNESS=1.6.
5. RECOMMENDED SOLDER THICKNESS=0.15



2	BRASS	TIN PLATED	T=0.64				
1	PPS	LIGHT GRAY		3	BRASS	TIN PLATED	
NO.	MATERIAL	FINISH .	REMARKS	NO.	MATERIAL	FINISH .	REMARKS
UNITS	mm	⊕	SCALE	2 : 1	△	COUNT	DESCRIPTION OF REVISIONS
APPROVED : AR. SHIRAI				09.08.08	DRAWING NO. EDC3-166162-02		
CHECKED : TY. TAKAHASHI				09.08.08	PART NO. GT25-8P-2. 2H(70)		
DESIGNED : TY. SAKASHITA				09.08.08	CODE NO. CL775-0001-3-70		
DRAWN : KT. MATSUDA				09.08.08	DATE		

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